

Application No. 10/008,853
Filed: 11/16/01
Group Art Unit: 2827

Please amend the title to read:

METHOD OF APPLYING FILLED NO-FLOW UNDERFILL

In the Claims

Please rewrite the indicated claims to read as follows:

11. A process for connecting an integrated circuit chip to a substrate comprising
- a. coating the connection area of said substrate with an underfill,
 - b. dipping said chip into a tacky thermosettable flux so that connection bumps of said chip are coated with said flux,
 - c. placing said chip having said flux onto said substrate so that the bumps of said chip are in contact with the pads of said substrate,
 - d. soldering said chip to said substrate, and
 - e. curing said underfill.